

# BTA312B series B and C

12 A Three-quadrant triacs high commutation

Rev. 01 — 12 April 2007

Product data sheet

## 1. Product profile

### 1.1 General description

Passivated, new generation, high commutation triacs in a SOT404 plastic single-ended surface-mountable package

### 1.2 Features

- Very high commutation performance maximized at each gate sensitivity
- High immunity to  $dV/dt$

### 1.3 Applications

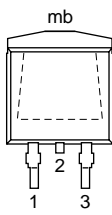
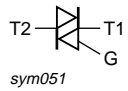
- High power motor control - e.g. washing machines, vacuum cleaners
- Refrigeration and air conditioning compressors
- Non-linear rectifier-fed motor loads
- Electronic thermostats

### 1.4 Quick reference data

- $V_{DRM} \leq 600$  V (BTA312B-600B/C)
- $V_{DRM} \leq 800$  V (BTA312B-800B/C)
- $I_{TSM} \leq 95$  A ( $t = 20$  ms)
- $I_{GT} \leq 50$  mA (BTA312B series B)
- $I_{GT} \leq 35$  mA (BTA312B series C)
- $I_{T(RMS)} \leq 12$  A

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Symbol
1	main terminal 1 (T1)		
2	main terminal 2 (T2)		
3	gate (G)		
mb	mounting base; main terminal 2 (T2)		

SOT404 (D2PAK)

### 3. Ordering information

**Table 2. Ordering information**

Type number	Package		Version
	Name	Description	
BTA312B-600B	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3-leads (one lead cropped)	SOT404
BTA312B-600C			
BTA312B-800B			
BTA312B-800C			

### 4. Limiting values

**Table 3. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DRM</sub>	repetitive peak off-state voltage	BTA312B-600B; BTA312B-600C	[1] -	600	V
		BTA312B-800B; BTA312B-800C	-	800	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; T <sub>mb</sub> ≤ 101 °C; see <a href="#">Figure 4</a> and <a href="#">5</a>	-	12	A
I <sub>TSM</sub>	non-repetitive peak on-state current	full sine wave; T <sub>j</sub> = 25 °C prior to surge; see <a href="#">Figure 2</a> and <a href="#">3</a>			
		t = 20 ms	-	95	A
		t = 16.7 ms	-	105	A
I <sup>2</sup> t	I <sup>2</sup> t for fusing	t = 10 ms	-	45	A <sup>2</sup> s
di <sub>T</sub> /dt	rate of rise of on-state current	I <sub>TM</sub> = 20 A; I <sub>G</sub> = 0.2 A; di <sub>G</sub> /dt = 0.2 A/μs	-	100	A/μs
I <sub>GM</sub>	peak gate current		-	2	A
P <sub>GM</sub>	peak gate power		-	5	W
P <sub>G(AV)</sub>	average gate power	over any 20 ms period	-	0.5	W
T <sub>stg</sub>	storage temperature		-40	+150	°C
T <sub>j</sub>	junction temperature		-	125	°C

[1] Although not recommended, off-state voltages up to 800 V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 A/μs.

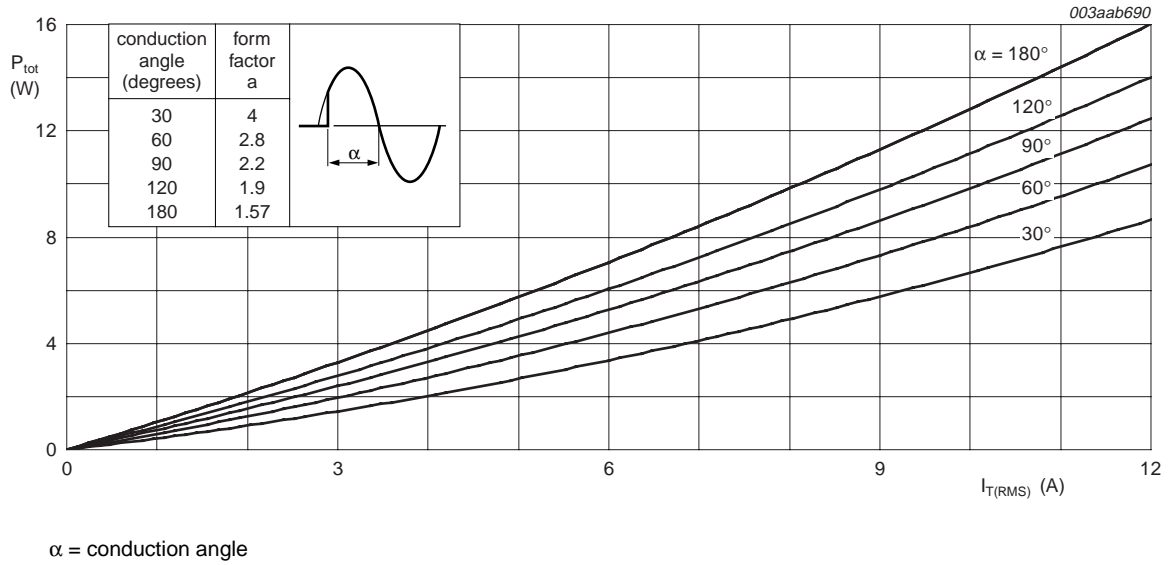


Fig 1. Total power dissipation as a function of RMS on-state current; maximum values

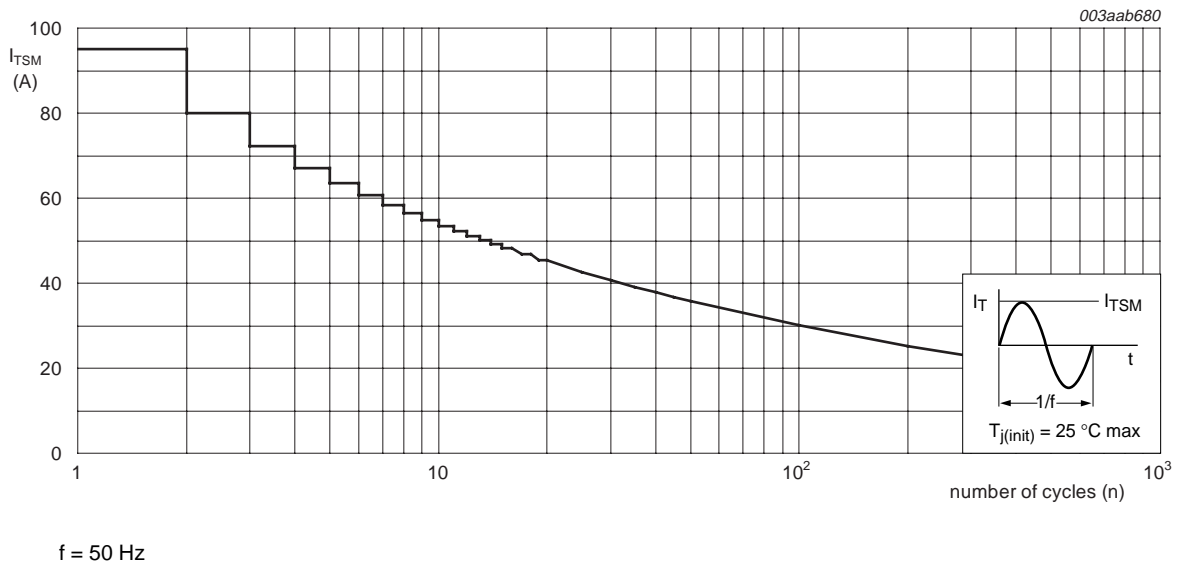
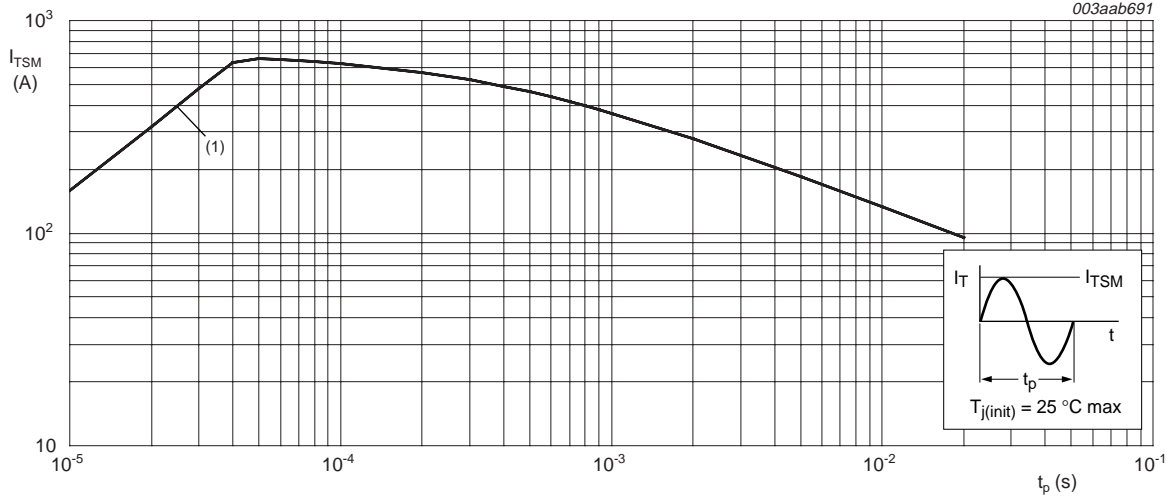


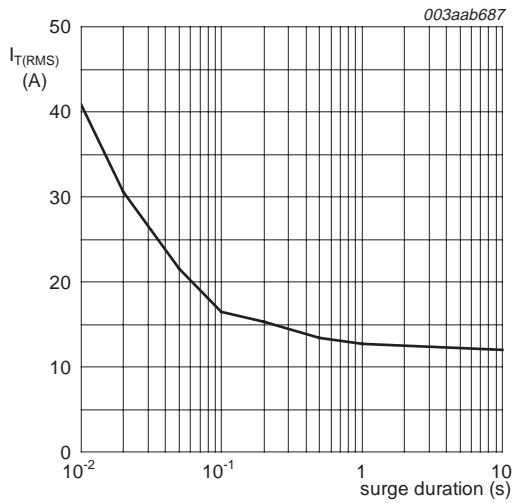
Fig 2. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20 \text{ ms}$

(1)  $di_T/dt$  limit

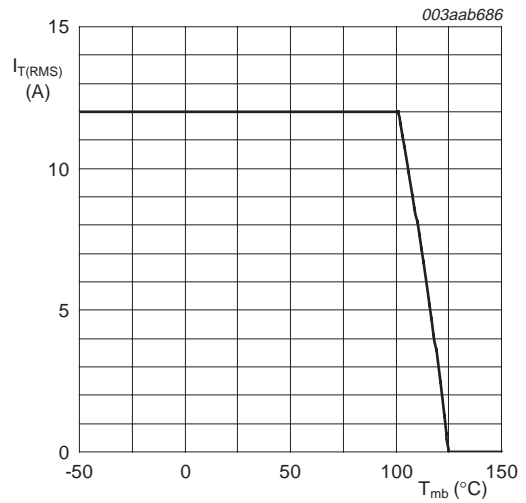
**Fig 3. Non-repetitive peak on-state current as a function of pulse duration; maximum values**



$f = 50 \text{ Hz}$

$T_{mb} = 101 \text{ °C}$

**Fig 4. RMS on-state current as a function of surge duration; maximum values**

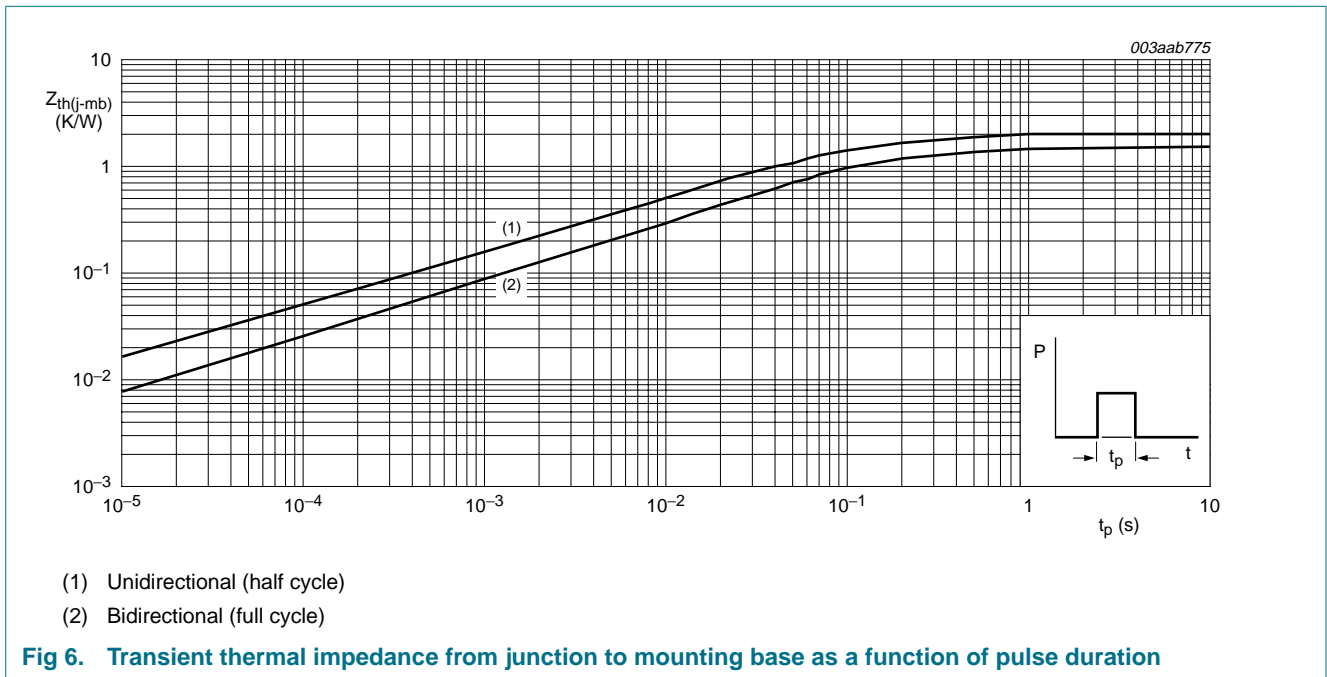


**Fig 5. RMS on-state current as a function of mounting base temperature; maximum values**

5. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	half cycle; see <a href="#">Figure 6</a>	-	-	2.0	K/W
		full cycle; see <a href="#">Figure 6</a>	-	-	1.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	mounted on a printed circuit board; minimum footprint	-	55	-	K/W



**6. Static characteristics**

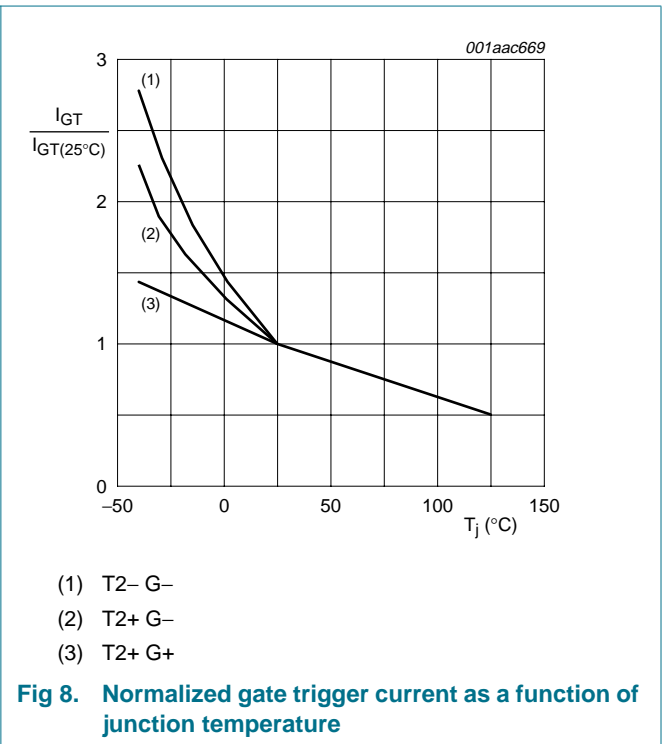
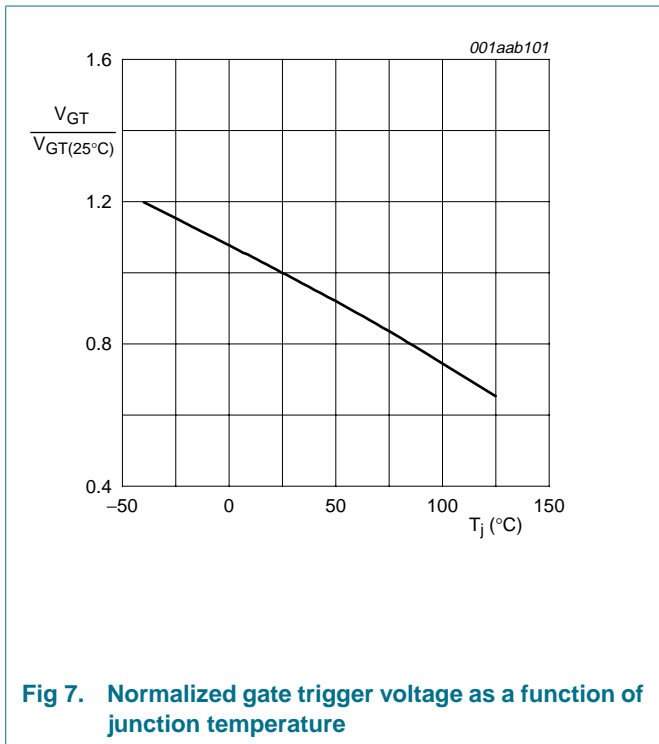
**Table 5. Static characteristics**  
*T<sub>j</sub> = 25 °C unless otherwise specified.*

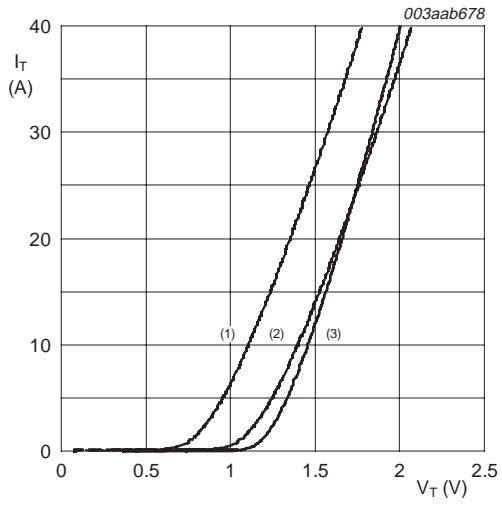
Symbol	Parameter	Conditions	BTA312B-600B BTA312B-800B			BTA312B-600C BTA312B-800C			Unit
			Min	Typ	Max	Min	Typ	Max	
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; see <a href="#">Figure 8</a>							
		T2+ G+	2	-	50	2	-	35	mA
		T2+ G-	2	-	50	2	-	35	mA
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; see <a href="#">Figure 10</a>							
		T2+ G+	-	-	60	-	-	50	mA
		T2+ G-	-	-	90	-	-	60	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; see <a href="#">Figure 11</a>	-	-	60	-	-	35	mA
		T2- G-	-	-	60	-	-	50	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 15 A; see <a href="#">Figure 9</a>	-	1.3	1.6	-	1.3	1.6	V
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; see <a href="#">Figure 7</a>	-	0.8	1.5	-	0.8	1.5	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 125 °C	0.25	0.4	-	0.25	0.4	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = V <sub>DRM(max)</sub> ; T <sub>j</sub> = 125 °C	-	0.1	0.5	-	0.1	0.5	mA

**7. Dynamic characteristics**

**Table 6. Dynamic characteristics**

Symbol	Parameter	Conditions	BTA312B-600B BTA312B-800B			BTA312B-600C BTA312B-800C			Unit
			Min	Typ	Max	Min	Typ	Max	
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 0.67 \times V_{DRM(max)}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; exponential waveform; gate open circuit	1000	2000	-	500	-	-	V/ $\mu\text{s}$
$di_{com}/dt$	rate of change of commutating current	$V_{DM} = 400\text{ V}$ ; $T_j = 125\text{ }^\circ\text{C}$ ; $I_{T(RMS)} = 12\text{ A}$ ; without snubber; gate open circuit	30	-	-	20	-	-	A/ms
$t_{gt}$	gate-controlled turn-on time	$I_{TM} = 20\text{ A}$ ; $V_D = V_{DRM(max)}$ ; $I_G = 0.1\text{ A}$ ; $di_G/dt = 5\text{ A}/\mu\text{s}$	-	2	-	-	2	-	$\mu\text{s}$



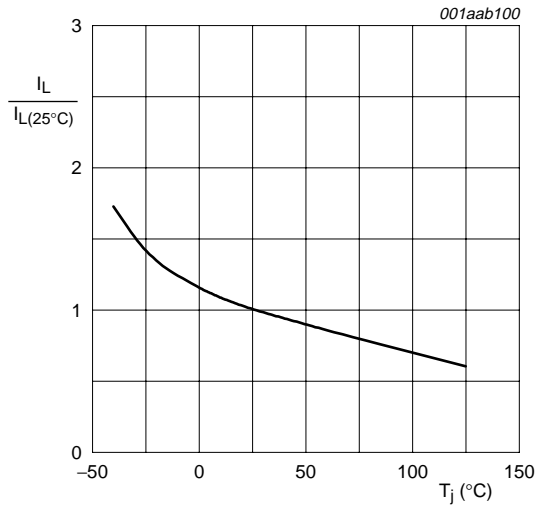


$V_o = 1.127 \text{ V}$

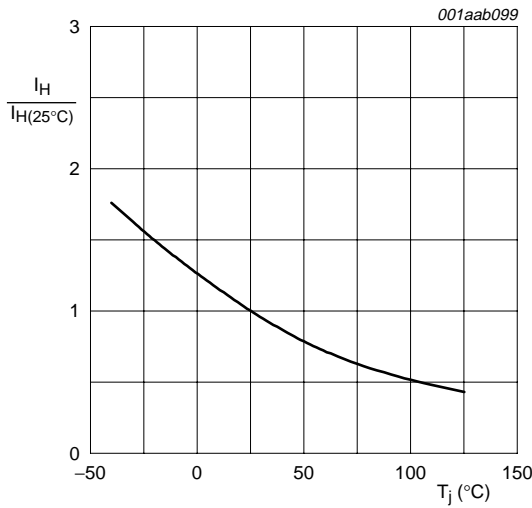
$R_s = 0.027 \text{ } \Omega$

- (1)  $T_j = 125 \text{ }^\circ\text{C}$ ; typical values
- (2)  $T_j = 125 \text{ }^\circ\text{C}$ ; maximum values
- (3)  $T_j = 25 \text{ }^\circ\text{C}$ ; maximum values

**Fig 9. On-state current as a function of on-state voltage**



**Fig 10. Normalized latching current as a function of junction temperature**



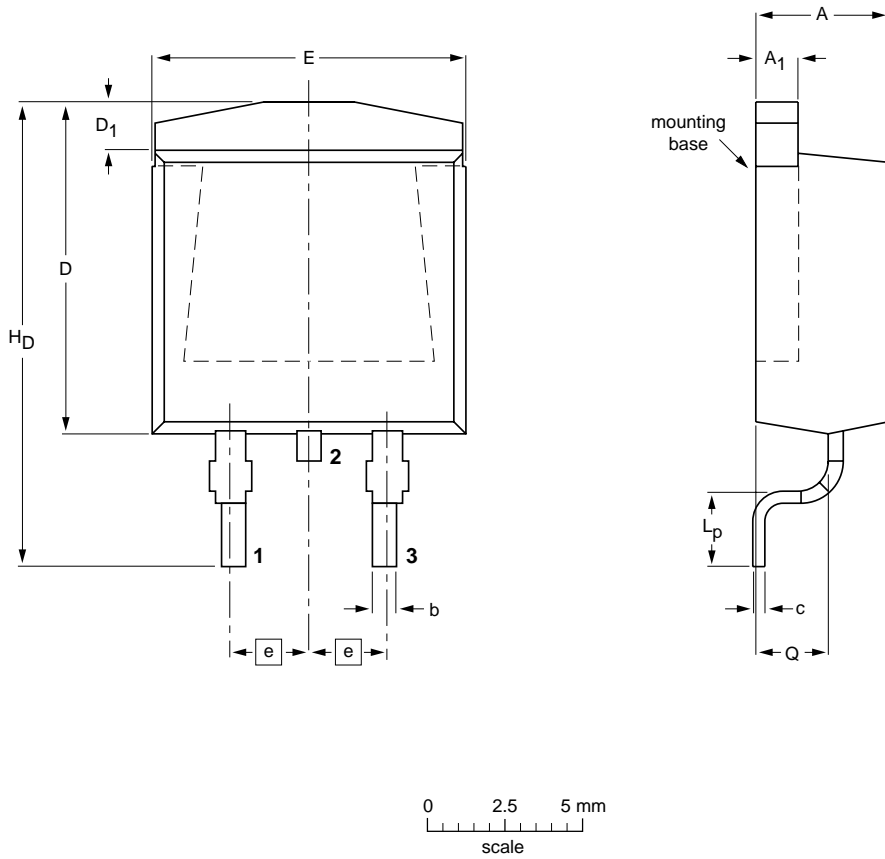
**Fig 11. Normalized holding current as a function of junction temperature**



**8. Package outline**

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

**SOT404**



**DIMENSIONS (mm are the original dimensions)**

UNIT	A	A <sub>1</sub>	b	c	D max.	D <sub>1</sub>	E	e	L <sub>p</sub>	H <sub>D</sub>	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.80 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT404						05-02-11 06-03-16

**Fig 12. Package outline SOT404 (D2PAK)**

## 9. Revision history

**Table 7. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BTA312B_SER_B_C_1	20070412	Product data sheet	-	-

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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